International Rectifier

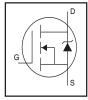
AUTOMOTIVE GRADE

AUIRFR2407

HEXFET® Power MOSFET

Features

- Advanced Planar Technology
- Low On-Resistance
- Dynamic dV/dT Rating
- 175°C Operating Temperature
- Fast Switching
- Fully Avalanche Rated
- Repetitive Avalanche Allowed up to Tjmax
- Lead-Free, RoHS Compliant
- Automotive Qualified*



V _{(BR)DSS}	75V
R _{DS(on)} typ.	21.8m $Ω$
max	26m $Ω$
I _{D (Silicon Limited)}	42A
	•

Description

Specifically designed for Automotive applications, this Stripe Planar design of HEXFET® Power MOSFETs utilizes the latest processing techniques to achieve low on-resistance per silicon area. This benefit combined with the fast switching speed and ruggedized device design that HEXFET power MOSFETs are well known for, provides the designer with an extremely efficient and reliable device for use in Automotive and a wide variety of other applications.



G	D	S
Gate	Drain	Source

Absolute Maximum Ratings

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only; and functional operation of the device at these or any other condition beyond those indicated in the specifications is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability. The thermal resistance and power dissipation ratings are measured under board mounted and still air conditions. Ambient temperature (T_A) is 25°C, unless otherwise specified.

	Parameter	Max.	Units
I _D @ T _C = 25°C	Continuous Drain Current, V _{GS} @ 10V	42	
I _D @ T _C = 100°C	Continuous Drain Current, VGS @ 10V	29	Α
I _{DM}	Pulsed Drain Current ①	170	
P _D @T _C = 25°C	Power Dissipation	110	W
	Linear Derating Factor	0.71	W/°C
V_{GS}	Gate-to-Source Voltage	± 20	V
E _{AS}	Single Pulse Avalanche Energy (Thermally Limited) ^②	130	mJ
I _{AR}	Avalanche Current ①	25	Α
E _{AR}	Repetitive Avalanche Energy ①	11	mJ
dv/dt	Peak Diode Recovery dv/dt ③	5.0	V/ns
T_J	Operating Junction and	-55 to + 175	
T _{STG}	Storage Temperature Range		°C
	Soldering Temperature, for 10 seconds (1.6mm from case)	300	

Thermal Resistance

	Parameter	Тур.	Max.	Units
$R_{\theta JC}$	Junction-to-Case ®		1.4	
$R_{\theta JA}$	Junction-to-Ambient (PCB Mount) ⑦		50	°C/W
$R_{\theta JA}$	Junction-to-Ambient		110	

HEXFET® is a registered trademark of International Rectifier.

^{*}Qualification standards can be found at http://www.irf.com/

Static Electrical Characteristics @ T_J = 25°C (unless otherwise specified)

	Parameter	Min.	Тур.	Max.	Units	Conditions
V _{(BR)DSS}	Drain-to-Source Breakdown Voltage	75			V	$V_{GS} = 0V, I_D = 250\mu A$
$\Delta V_{(BR)DSS}/\Delta T_{J}$	Breakdown Voltage Temp. Coefficient		0.078		V/°C	Reference to 25°C, I _D = 1mA
R _{DS(on)}	Static Drain-to-Source On-Resistance		21.8	26.0	mΩ	$V_{GS} = 10V, I_D = 25A$ ④
V _{GS(th)}	Gate Threshold Voltage	2.0		4.0	V	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$
gfs	Forward Transconductance	27			S	$V_{DS} = 25V, I_D = 25A^{\textcircled{4}}$
I _{DSS}	Drain-to-Source Leakage Current			20	μΑ	$V_{DS} = 75V, V_{GS} = 0V$
				250		$V_{DS} = 60V, V_{GS} = 0V, T_{J} = 150^{\circ}C$
I _{GSS}	Gate-to-Source Forward Leakage			200	nA	$V_{GS} = 20V$
	Gate-to-Source Reverse Leakage			-200		$V_{GS} = -20V$

Dynamic Electrical Characteristics @ T_J = 25°C (unless otherwise specified)

Parameter	Min.	Тур.	Max.	Units	Conditions
Total Gate Charge		74	110		I _D = 25A
Gate-to-Source Charge		13	19	nC	$V_{DS} = 60V$
Gate-to-Drain ("Miller") Charge		22	34		V _{GS} = 10V ④
Turn-On Delay Time		16			$V_{DD} = 38V$
Rise Time		90			$I_D = 25A$
Turn-Off Delay Time		65		ns	$R_G = 6.8\Omega$
Fall Time		66			V _{GS} = 10V ④
Internal Drain Inductance		4.5			Between lead,
				nΗ	6mm (0.25in.)
Internal Source Inductance		7.5			from package
					and center of die contact
Input Capacitance		2400			$V_{GS} = 0V$
Output Capacitance		340		pF	$V_{DS} = 25V$
Reverse Transfer Capacitance		77			f = 1.0MHz, See Fig. 5
Output Capacitance		15700			$V_{GS} = 0V, V_{DS} = 1.0V, f = 1.0MHz$
Output Capacitance		220			$V_{GS} = 0V, V_{DS} = 60V, f = 1.0MHz$
Effective Output Capacitance (5)		220			$V_{GS} = 0V$, $V_{DS} = 0V$ to $60V$
	Total Gate Charge Gate-to-Source Charge Gate-to-Drain ("Miller") Charge Turn-On Delay Time Rise Time Turn-Off Delay Time Fall Time Internal Drain Inductance Internal Source Inductance Input Capacitance Output Capacitance Output Capacitance Output Capacitance Output Capacitance Output Capacitance Output Capacitance	Total Gate Charge —— Gate-to-Source Charge —— Gate-to-Drain ("Miller") Charge —— Turn-On Delay Time —— Rise Time —— Turn-Off Delay Time —— Fall Time —— Internal Drain Inductance —— Internal Source Inductance —— Input Capacitance —— Output Capacitance ——	Total Gate Charge — 74 Gate-to-Source Charge — 13 Gate-to-Drain ("Miller") Charge — 22 Turn-On Delay Time — 16 Rise Time — 90 Turn-Off Delay Time — 65 Fall Time — 66 Internal Drain Inductance — 4.5 Internal Source Inductance — 7.5 Input Capacitance — 2400 Output Capacitance — 340 Reverse Transfer Capacitance — 77 Output Capacitance — 15700 Output Capacitance — 220	Total Gate Charge — 74 110 Gate-to-Source Charge — 13 19 Gate-to-Drain ("Miller") Charge — 22 34 Turn-On Delay Time — 16 — Rise Time — 90 — Turn-Off Delay Time — 65 — Fall Time — 66 — Internal Drain Inductance — 4.5 — Internal Source Inductance — 7.5 — Input Capacitance — 2400 — Output Capacitance — 340 — Reverse Transfer Capacitance — 77 — Output Capacitance — 15700 — Output Capacitance — 220 —	Total Gate Charge — 74 110 Gate-to-Source Charge — 13 19 Gate-to-Drain ("Miller") Charge — 22 34 Turn-On Delay Time — 16 — Rise Time — 90 — Turn-Off Delay Time — 65 — Fall Time — 66 — Internal Drain Inductance — 4.5 — Internal Source Inductance — 7.5 — Input Capacitance — 2400 — Output Capacitance — 340 — Reverse Transfer Capacitance — 77 — Output Capacitance — 15700 — Output Capacitance — 220 —

Diode Characteristics

	Parameter	Min.	Тур.	Max.	Units	Conditions
Is	Continuous Source Current			42		MOSFET symbol
	(Body Diode)				Α	showing the
I _{SM}	Pulsed Source Current			170		integral reverse
	(Body Diode) ①					p-n junction diode.
V_{SD}	Diode Forward Voltage			1.3	V	$T_J = 25^{\circ}C$, $I_S = 25A$, $V_{GS} = 0V$ ④
t _{rr}	Reverse Recovery Time		100	150	ns	$T_J = 25^{\circ}C, I_F = 25A$
Q _{rr}	Reverse Recovery Charge		400	600	nC	di/dt = 100A/μs ④
t _{on}	Forward Turn-On Time	Intrinsion	Intrinsic turn-on time is negligible (turn-on is dominated by LS+LD)			

Notes

- ① Repetitive rating; pulse width limited by max. junction temperature.
- $\text{ Starting T}_J = 25^{\circ}\text{C}, \ L = 0.42\text{mH} \\ \text{R}_G = 25\Omega, \ \text{I}_{AS} = 25\text{A}.$
- $\label{eq:local_system} \begin{tabular}{ll} \begin{tabular}{ll} $I_{SD} \le 25A, \ di/dt \le 290A/\mu s, \ V_{DD} \le V_{(BR)DSS}, \\ $T_J \le 175^{\circ}C. \end{tabular}$
- 4 Pulse width \leq 300 μ s; duty cycle \leq 2%.
- $\ ^{\circ}$ C $_{\circ SS}$ eff. is a fixed capacitance that gives the same charging time as C $_{\circ SS}$ while V $_{DS}$ is rising from 0 to 80% V $_{DSS}.$
- When mounted on 1" square PCB (FR-4 or G-10 Material) . For recommended footprint and soldering techniques refer to application note #AN-994.
- $\ensuremath{\mathfrak{D}}$ R_θ is measured at T_J of approximately 90°C.

Qualification Information[†]

Qualification Level		Automotive (per AEC-Q101) ^{††}			
		Comments: This part number(s) passed Automotive qualification. IR's Industrial and Consumer qualification level is granted by extension of the higher Automotive level.			
Moisture Sensitivity Level		D-Pak MSL1			
Machine Model Human Body Model		Class M4 (+/- 500V) ††† AEC-Q101-002			
		Class H1C (+/- 2000V) ††† AEC-Q101-001			
	Charged Device Model	Class C5 (+/- 2000V) ††† AEC-Q101-005			
RoHS Comp	oliant	Yes			

[†] Qualification standards can be found at International Rectifier's web site: http://www.irf.com/

^{††} Exceptions (if any) to AEC-Q101 requirements are noted in the qualification report.

^{†††} Highest passing voltage.

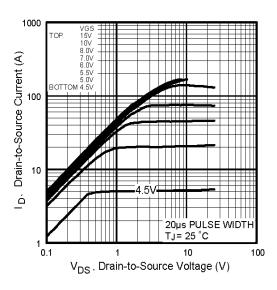
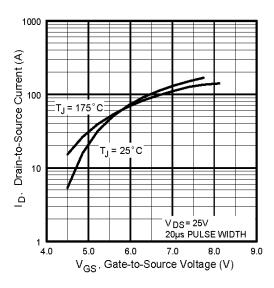


Fig 1. Typical Output Characteristics

Fig 2. Typical Output Characteristics



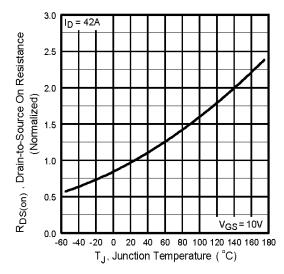


Fig 3. Typical Transfer Characteristics

Fig 4. Normalized On-Resistance Vs. Temperature

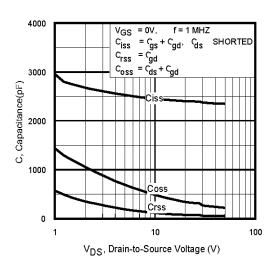


Fig 5. Typical Capacitance Vs. Drain-to-Source Voltage

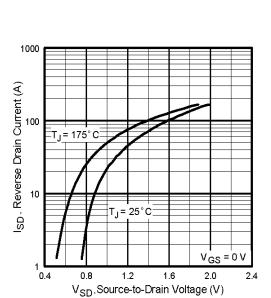


Fig 7. Typical Source-Drain Diode Forward Voltage

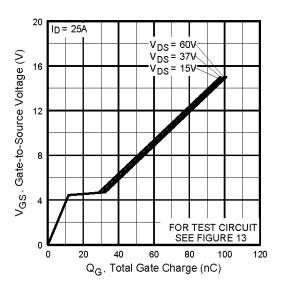


Fig 6. Typical Gate Charge Vs. Gate-to-Source Voltage

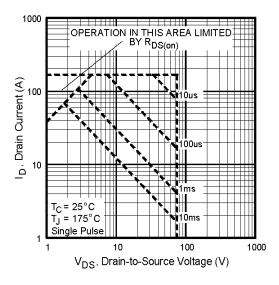


Fig 8. Maximum Safe Operating Area

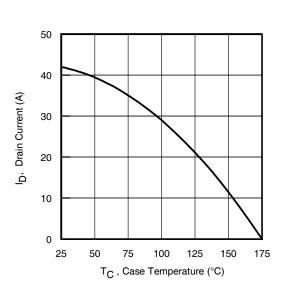


Fig 9. Maximum Drain Current Vs. Case Temperature

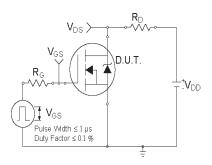


Fig 10a. Switching Time Test Circuit

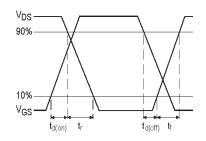


Fig 10b. Switching Time Waveforms

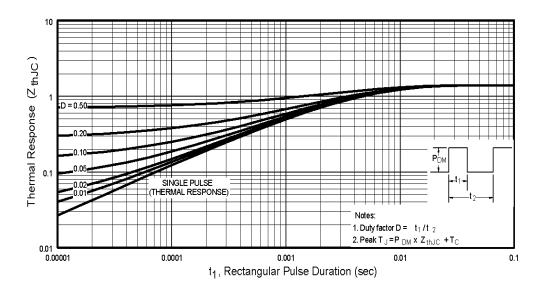


Fig 11. Maximum Effective Transient Thermal Impedance, Junction-to-Case

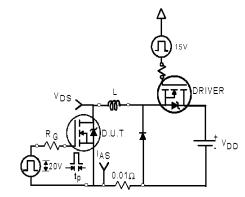


Fig 12a. Unclamped Inductive Test Circuit

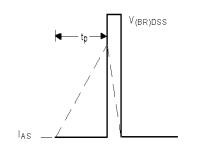


Fig 12b. Unclamped Inductive Waveforms

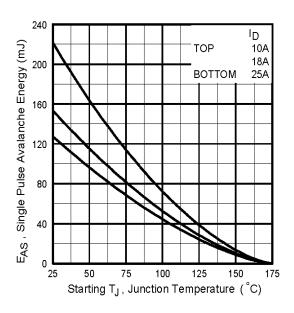


Fig 12c. Maximum Avalanche Energy Vs. Drain Current

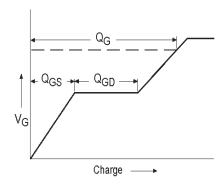


Fig 13a. Basic Gate Charge Waveform

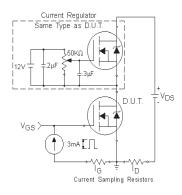
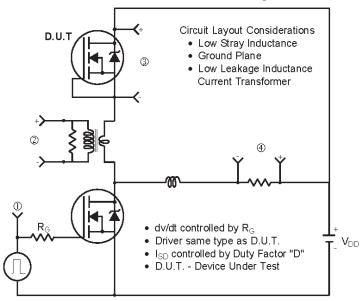


Fig 13b. Gate Charge Test Circuit

Peak Diode Recovery dv/dt Test Circuit



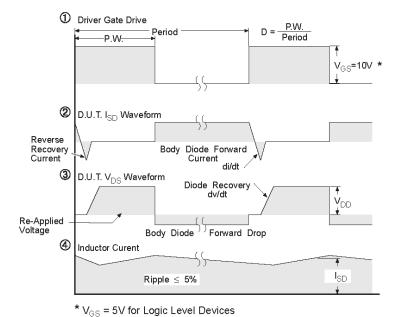
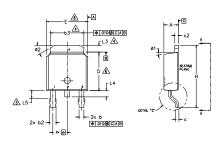
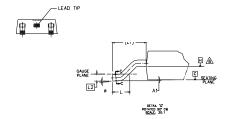


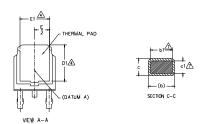
Fig 14. For N-Channel HEXFET® Power MOSFETs

D-Pak (TO-252AA) Package Outline

Dimensions are shown in millimeters (inches)







- 2.- DIMENSION ARE SHOWN IN INCHES [MILLIMETERS].
- LEAD DIMENSION UNCONTROLLED IN L5.

- AST LEAD DIMENSION UNCONTROLLED IN LS.

 DIMENSION DI, EL, LS & SE SETABLISH A MINIMUM MOUNTING SUBFACE FOR THERMAL PAD.

 5.— SECTION C-C DIMENSIONS APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN .005 AND 0.10
 [0.13 AND 0.25] FROM THE LEAD TIP.

 DIMENSION D & ED ON TINCLUEE MOLD FLASH, MOLD FLASH SHALL NOT EXCEED .005 [0.13] PER SIDE. THESE DIMENSIONS ARE MEASURED AT THE OUTMOST EXTREMES OF THE PLASTIC BODY.
- DIMENSION bI & c1 APPLIED TO BASE METAL ONLY.

9,-	OUTLINE	CONFORMS	TO	JEDEC	OUTLINE	TO-252AA.

S Y M		DIMEN	ISIONS		N.
В	MILLIM	ETERS	INC	HES	O T
O L	MIN.	MAX.	MIN.	MAX.	E S
Α	2,18	2,39	.086	.094	
A1	-	0.13	-	.005	
ь	0,64	0.89	.025	.035	
ь1	0.65	0.79	.025	.031	7
b2	0.76	1,14	.030	.045	
ь3	4.95	5.46	.195	.215	4
С	0,46	0,61	.018	.024	
с1	0.41	0.56	.016	.022	7
c2	0.46	0.89	.018	.035	
D	5,97	6.22	.235	.245	6
D1	5.21	-	.205	-	4
Ε	6.35	6.73	.250	.265	6
E1	4,32	-	.170	-	4
e	2.29 BSC		.090	BSC	
н	9.40	10.41	.370	.410	
L	1.40	1.78	.055	.070	
L1	2,74	BSC	.108	REF,	
L2	0.51	BSC	.020	BSC	
L3	0.89	1.27	.035	.050	4
L4	-	1.02	-	.040	
L5	1,14	1.52	.045	.060	3
ø	0.	10*	0.	10*	
ø1	0,	15*	0,	15*	
ø2	25*	35*	25*	35*	

LEAD ASSIGNMENTS

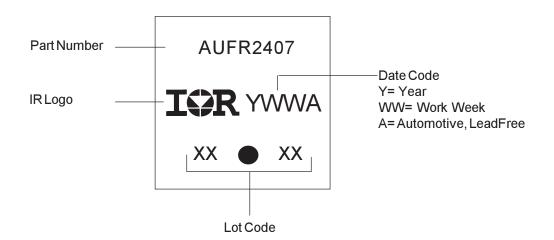
HEXFET

- 1.- GATE 2.- DRAIN 3.- SOURCE 4.- DRAIN

IGBT & CoPAK

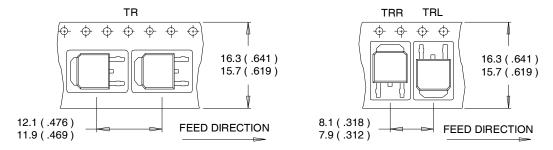
- 1.- GATE
 2.- COLLECTOR
 3.- EMITTER
 4.- COLLECTOR

D-Pak Part Marking Information



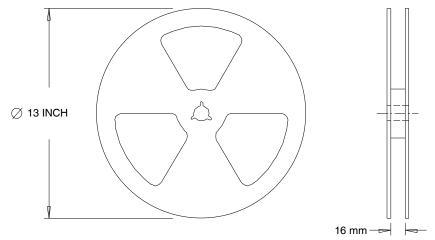
D-Pak (TO-252AA) Tape & Reel Information

Dimensions are shown in millimeters (inches)



NOTES:

- 1. CONTROLLING DIMENSION: MILLIMETER.
- 2. ALL DIMENSIONS ARE SHOWN IN MILLIMETERS (INCHES).
- 3. OUTLINE CONFORMS TO EIA-481 & EIA-541.



NOTES:

1. OUTLINE CONFORMS TO EIA-481.

Ordering Information

Base part number	Package Type	Standard Pack		Complete Part Number
		Form	Quantity	
AUIRFR2407	Dpak	Tube	75	AUIRFR2407
		Tape and Reel	2000	AUIRFR2407TR
		Tape and Reel Left	3000	AUIRFR2407TRL
		Tape and Reel Right	3000	AUIRFR2407TRR

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